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128K x 32 SRAM MODULE

PUMA 68S4000X - 12/15/20/25

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Description

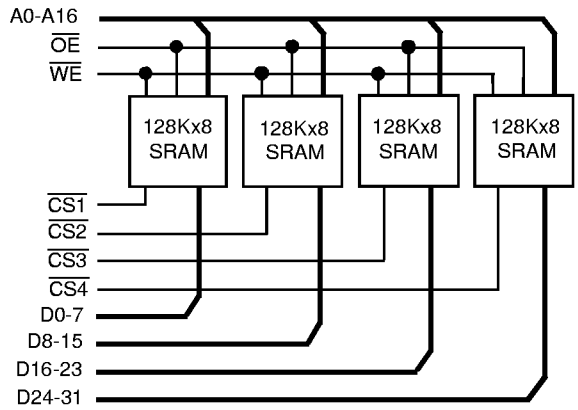
The PUMA68S4000X is a 4Mbit CMOS High Speed Static RAM organised as 128K x 32 in a JEDEC 68 pin surface mount PLCC, available with access times of 15ns, 20ns, or 25ns. The output width is user configurable as 8 , 16 or 32 bits using four Chip Selects ($\overline{CS1}$~4).

The device features low power standby, multiple ground pins for maximum noise immunity and TTL compatible inputs and outputs. The PUMA 68S4000X offers a dramatic space saving advantage over four standard 128Kx8 devices. A low power standby option with 2V data retention mode is available.

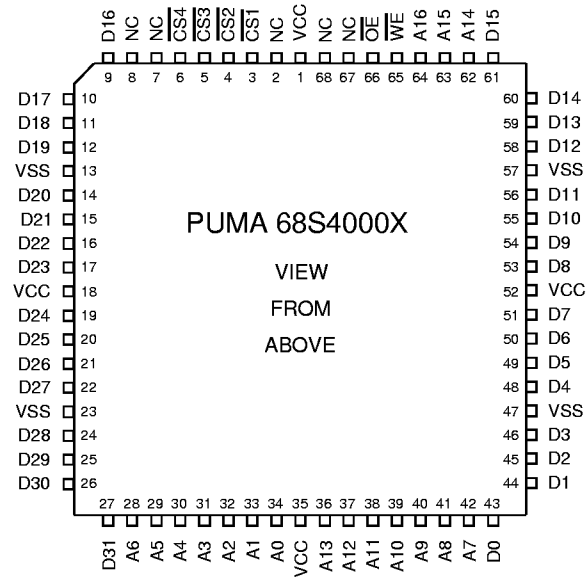
Features

- Very Fast Access Times of 12/15/20/25 ns.
- JEDEC 68 'J' leaded plastic surface mount Substrate
- Upgradeable footprint.
- User Configurable as 8 / 16 / 32 bit wide output.
- Operating Power (32-BIT) 4.40 W (Max)
  Low Power Standby (TTL) 1.32 W (Max)
  -L Version (CMOS) 44 mW (Max)
- Fully Static operation.
- Multiple ground pins for maximum noise immunity.
- Single 5V±10% Power supply.

Block Diagram



Pin Definition



Pin Functions

Address Inputs	**A0 - A16**
Data Input/Output	**D0 - D31**
Chip Select	**$\overline{CS1}$~4**
Write Enable	**$\overline{WE}$**
Output Enable	**$\overline{OE}$**
No Connect	**NC**
Power (+5V)	**V_{cc}**
Ground	**GND**

Package Details

Plastic 68 J-Leaded JEDEC PLCC

DC OPERATING CONDITIONS

Absolute Maximum Ratings (1)

Voltage on any pin relative to GND	V_T	-0.3 to +7.0	V
Power Dissipation	P_T	4.0	W
Storage Temperature	T_{STG}	-55 to +125	℃
DC Output Current	I_{OUT}	80	mA

Notes (1) Stresses above those listed may cause permanent damage. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	*Symbol*	*min*	*typ*	*max*	*Units*	
Supply Voltage	V_{CC}	4.5	5.0	5.5	V	
Max Terminal Voltage	V_{TERM}	-0.3	-	7.0	V	
Input High Voltage	V_{IH}	2.2	-	Vcc+0.3	V	
Input Low Voltage	V_{IL} (1)	-0.3	-	0.8	V	
Operating Temperature	T_A	0	-	70	℃	
	T_{AI}	-40	-	85	℃	(Suffix **I**)

Notes: (1) Pulse width: -3.0V for less than 5ns.

DC Electrical Characteristics (V_{CC}=5V±10%,T_A=-40°C to +85°C)

Parameter		*Symbol*	*Test Condition*	*min*	*typ*	*max*	*Unit*
Input Leakage Current		I_{LI1}	V_{IN}=0V to V_{CC}	-20	-	20	µA
Output Leakage Current		I_{LO}	$V_{I/O}$=0V to V_{CC}	-40	-	40	µA
Operating Supply Current(2)	32 bit	I_{CC32}	$\overline{CS}$(1)=V_{IL}, $I_{I/O}$=0mA, f=f_{max}	-	-	840	mA
	16 bit	I_{CC16}	As above.	-	-	540	mA
	8 bit	I_{CC8}	As above.	-	-	400	mA
Standby Supply Current	(TTL)	I_{SB}	$\overline{CS}$(1)=V_{IH}, f=f_{max}, V_{IN}=V_{IL} or V_{IH}	-	-	260	mA
-L Version	(CMOS)	I_{SB1}	$\overline{CS}$≥V_{CC}-0.2V, 0.2V≥V_{IN}≥V_{CC}-0.2V,f=0	-	-	8	mA
Output Voltage Low		V_{OL}	I_{OL} = 8.0mA,V_{CC}=Min	-	-	0.4	V
Output Voltage High		V_{OH}	I_{OH} = -4.0mA,V_{CC}=Min	2.4	-	-	V

Notes: (1) $\overline{CS}$1~4 inputs operate simultaneously for 32 bit mode, in pairs for 16 bit mode and singly for 8 bit mode.

(2) At f=f_{max} address and data inputs are cycling at max frequency.

Capacitance (V_{CC}=5V, T_A=25°C, F=1Mhz)

Parameter	*Symbol*	*Test Condition*	*min*	*typ*	*max*	*Unit*
Input Capacitance Address,$\overline{OE}$,$\overline{WE}$	C_{IN1}	V_{IN}=0V	-	-	34	pF
Output Capacitance 8-bit mode (worst case)	$C_{I/O}$	$V_{I/O}$=0V	-	-	42	pF

Note: These parameters are calculated, not measured.

AC Test Conditions

*Input pulse levels: 0.0V to 3.0V

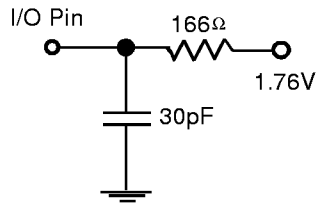
*Input rise and fall times: 3 ns

*Input and Output timing reference levels: 1.5V

*V_{cc}=5V±10%

*PUMA module is tested in 32 bit mode.

Output Load



Operation Truth Table

$\overline{CS1}$	$\overline{CS2}$	$\overline{CS3}$	$\overline{CS4}$	$\overline{OE}$	$\overline{WE}$	SUPPLY CURRENT	MODE
L	H	H	H	X	L	I_{CC8}	Write $D_{0\sim7}$
H	L	H	H	X	L	I_{CC8}	Write $D_{8\sim15}$
H	H	L	H	X	L	I_{CC8}	Write $D_{16\sim23}$
H	H	H	L	X	L	I_{CC8}	Write $D_{24\sim31}$
L	L	H	H	X	L	I_{CC16}	Write $D_{0\sim15}$
H	H	L	L	X	L	I_{CC16}	Write $D_{16\sim31}$
L	L	L	L	X	L	I_{CC32}	Write $D_{0\sim31}$
L	H	H	H	L	H	I_{CC8}	Read $D_{0\sim7}$
H	L	H	H	L	H	I_{CC8}	Read $D_{8\sim15}$
H	H	L	H	L	H	I_{CC8}	Read $D_{16\sim23}$
H	H	H	L	L	H	I_{CC8}	Read $D_{24\sim31}$
L	L	H	H	L	H	I_{CC16}	Read $D_{0\sim15}$
H	H	L	L	L	H	I_{CC16}	Read $D_{16\sim31}$
L	L	L	L	L	H	I_{CC32}	Read $D_{0\sim31}$
X	X	X	X	H	H	$I_{CC32}/I_{CC16}/I_{CC8}$	$D_{0\sim31}$ High-Z
H	H	H	H	X	X	I_{SB}, I_{SB1}	$D_{0\sim31}$ Standby

Notes : H = V_{IH} : L =V_{IL} : X = V_{IH} or V_{IL}

Low Vcc Data Retention Characteristics - L version only

Parameter	*Symbol*	*Test Condition*	*min*	*typ*	*max*	*Unit*
V_{CC} for Data Retention	V_{DR}	$\overline{CS}$=V_{CC}-0.2V	2.0	-	-	V
Data Retention Current	I_{CCDR1} (1)	V_{CC} = 2.0V, $\overline{CS}$ > V_{CC}-0.2V, V_{IN} >0V	-	-	2.2	mA
Data Retention Time	t_{CDR}	See Retention Waveform	0	-	-	ns
Operation Recovery Time	t_R	See Retention Waveform	t_{RC}	-	-	ns

AC OPERATING CONDITIONS

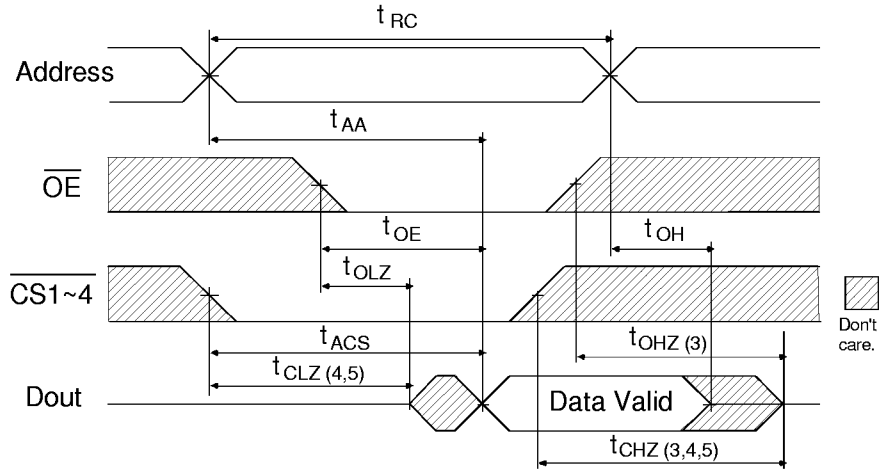
Read Cycle

		12		15		20		25		
Parameter	*Symbol*	*min*	*max*	*min*	*max*	*min*	*max*	*min*	*max*	*Units*
Read Cycle Time	t_{RC}	12	-	15	-	20	-	25	-	ns
Address Access Time	t_{AA}	-	12	-	15	-	20	-	25	ns
Chip Select Access Time	t_{ACS}	-	12	-	15	-	20	-	25	ns
Output Enable to Output Valid	t_{OE}	-	7	-	8	-	10	-	13	ns
Output Hold from Address Change	t_{OH}	3	-	3	-	3	-	3	-	ns
Chip Selection to Output in Low Z	t_{CLZ}	2	-	2	-	3	-	3	-	ns
Output Enable to Output in Low Z	t_{OLZ}	0	-	0	-	0	-	0	-	ns
Chip Deselection to Output in High Z	t_{CHZ}	0	6	0	8	0	9	0	10	ns
Output Disable to Output in High Z	t_{OHZ}	0	5	0	7	0	8	0	10	ns

Write Cycle

		12		15		20		25		
Parameter	*Symbol*	*min*	*max*	*min*	*max*	*min*	*max*	*min*	*max*	*Units*
Write Cycle Time	t_{WC}	12	-	15	-	20	-	25	-	ns
Chip Selection to End of Write	t_{CW}	10	-	12	-	15	-	20	-	ns
Address Valid to End of Write	t_{AW}	10	-	12	-	15	-	20	-	ns
Address Setup Time	t_{AS}	0	-	0	-	0	-	0	-	ns
Write Pulse Width	t_{WP}	10	-	12	-	15	-	20	-	ns
Write Recovery Time	t_{WR}	0	-	0	-	0	-	0	-	ns
Data to Write Time Overlap	t_{DW}	7	-	9	-	12	-	15	-	ns
Output Active from End of Write	t_{OW}	0	-	0	-	0	-	0	-	ns
Data Hold from Write Time	t_{DH}	0	-	0	-	0	-	0	-	ns
Write to Output High Z	t_{WHZ}	6	-	-	7	-	10	-	12	ns

Read Cycle Timing Waveform (1,2)



AC Read Characteristics Notes

(1) $\overline{WE}$ is High for Read Cycle.

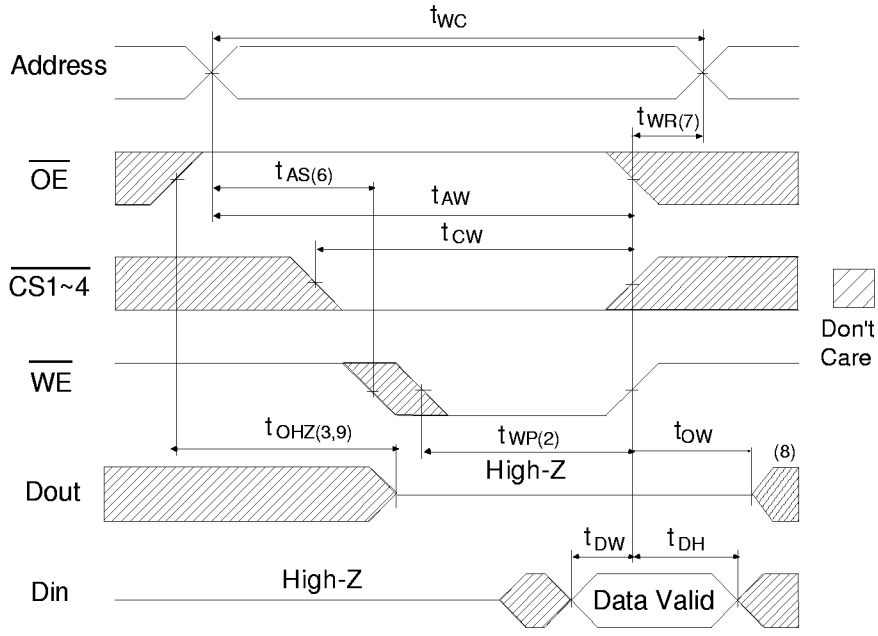
(2) All read cycle timing is referenced from the last valid address to the first transition address.

(3) t_{CHZ} and t_{OHZ} are defined as the time at which the outputs achieve open circuit conditions and are not referenced to output voltage levels.

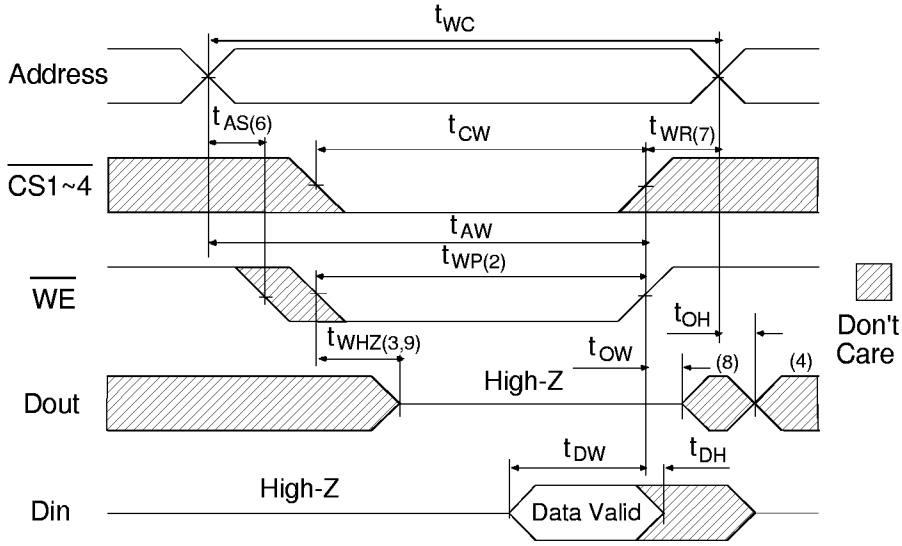
(4) At any given temperature and voltage condition, t_{CHZ} (max) is less than t_{CLZ} (min) both for a given module and from module to module.

(5) These parameters are sampled and not 100% tested.

Write Cycle No.1 Timing Waveform (1,4)



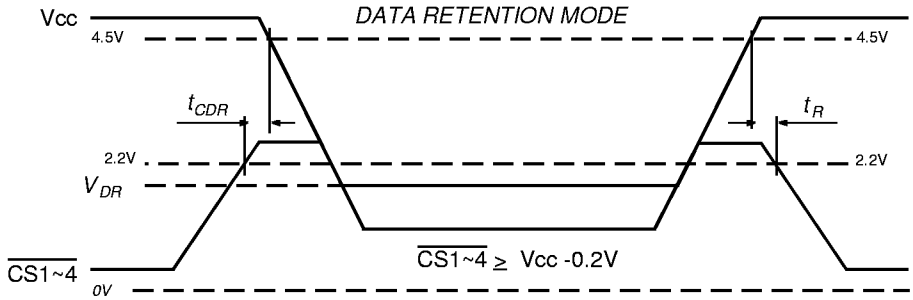
Write Cycle No.2 Timing Waveform (1,5)



AC Write Characteristics Notes

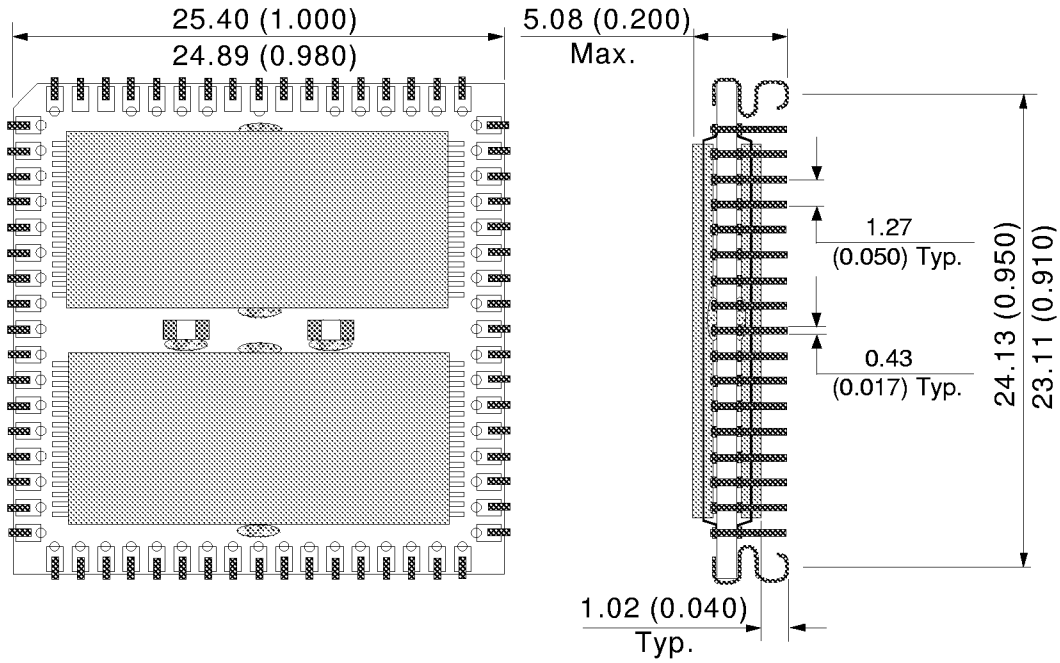
(1) All write cycle timing is referenced from the last valid address to the first transition address.
(2) All writes occur during the overlap of $\overline{CS1\sim4}$ and $\overline{WE}$ low.
(3) If $\overline{OE}$, $\overline{CS1\sim4}$, and $\overline{WE}$ are in the Read mode during this period, the I/O pins are low impedance state. Inputs of opposite phase to the output must not be applied because bus contention can occur.
(4) Dout is the Read data of the new address.
(5) $\overline{OE}$ is continuously low.
(6) Address is valid prior to or coincident with $\overline{CS1\sim4}$ and $\overline{WE}$ low, too avoid inadvertant writes.
(7) $\overline{CS1\sim4}$ or $\overline{WE}$ must be high during address transitions.
(8) When CS is low : I/O pins are in the output state. Input signals of opposite phase leading to the output should not be applied.
(9) Defined as the time at which the outputs achieve open circuit conditions and are not referenced to output voltage levels. These parameters are sampled and not 100% tested.

Data Retention Waveform



Package Information Dimensions in mm(inches)

Plastic 68 Pin JEDEC Surface mount PLCC



Ordering Information

PUMA 68S4000XLI - 15

Speed	12	=	12 ns
	15	=	15 ns
	20	=	20 ns
	25	=	25 ns
Temp. range/screening	Blank	=	Commercial Temperature
	I	=	Industrial Temperature
Power Consumption	Blank	=	Standard
	L	=	Low Power
Pinout Configuration	X	=	Industry Standard Pinout
Memory Organisation	S4000	=	128K x 32 SRAM configurable as 256K x 16 and 512K x 8
Package	PUMA 68	=	68 pin "J" Leaded PLCC

Soldering Recommendations.

Bake.

As specified on product packaging.

If not specified HMP Ltd. recommend a minimum bake of 6 hours duration @ 125°C, if parts have been exposed to the atmosphere for 24 hours or more.

Soldering.

Must not exceed,

VPR 215 - 219°C, 60 secs.

IR / Convection

Ramp Rate 6°C/sec max.
Temp maintained at 125°C,120 secs max.
Temp exceeding 183°C, 120 - 180 secs.
Time at max. temp. 10 - 40 secs.
Max temp. 220 +5/-0°C
Ramp down -6°C/sec max.